

PRODUCT DATA SHEET

SikaBond[®]-T17

ONE-COMPONENT, LOW ODOR, POLYURETHANE ADHESIVE FOR WOOD FLOORING

PRODUCT DESCRIPTION

SikaBond[®]-T17 is a one-component, low odor, moisture cured polyurethane adhesive for full surface bonding of wood flooring. SikaBond[®]-T17 will tenaciously bond wood to most surfaces, including concrete, plywood, and leveling and patch underlayments that have been properly prepared.

USES

SikaBond[®]-T17 may be used to bond all engineered wood flooring, solid flat-milled shorts and solid shorts designed by the manufacturer for glue down applications. This adhesive can also be used for many other bonding applications that are common for light commercial and residential applications including acoustic rubber underlayment systems.

CHARACTERISTICS / ADVANTAGES

- 100% Elongation
- Bond up to 3/4" solid and engineered wood
- Low odor
- Excellent workability
- Fast curing
- Suitable for common types of wood floors
- Suitable for in-floor radiant heat installation
- Contains no water
- Tenacious bond

APPROVALS / STANDARDS

LEED [®] EQc 4.1 (100 g/L limit)	SCAQMD, Rule 1168 (100 g/L limit)	BAAQMD, Reg. 8, Rule 51 (120 g/L limit)
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PRODUCT INFORMATION





Chemical Base	1-component, moisture cured polyurethane.
Packaging	4 gal. (15 L) pail
Color	Light Yellow
Shelf Life	12 months from date of production if stored in undamaged original sealed containers per storage requirements
Storage Conditions	In dry conditions and protected from direct sunlight at temperatures between 50 °F and 70 °F (10–25 °C). Condition material to 65–75 °F (18–24 °C) before using.



TECHNICAL INFORMATION

Shore A Hardness	~ 50	(28 days at 75 °F (23 °C) and 50 % R.H.)
Tensile Strength	150 psi	(28 days at 75 °F (23 °C) and 50 % R.H.)
Elongation at Break	~ 100 % cured	(at 75 °F (23 °C) and 50 % R.H.)
Service Temperature	-40°F to +158°F	


APPLICATION INFORMATION

Coverage

FOR USE AS ADHESIVE ONLY			
Flooring Type		Trowel	Coverage
Solid	Max Thickness: 3/4" Max Width: 5'	1/4" x 1/4" x 1/4" Square notch 	30 sq.ft. per gal.
Engineered	Thickness: >1/2" Max Width: Unlimited	1/4" x 1/4" x 1/8" Square notch 	35-40 sq.ft. per gal.
Engineered	Thickness: <1/2" Max Width: Unlimited	P5: 3/16" x 3/16" x 3/16" Flat V-notch 	45-50 sq.ft. per gal.
		3/16" x 5/32" V-Notch 	50 sq.ft. per gal.

FOR ALL-IN-ONE MOISTURE AND SOUND CONTROL			
Flooring Type		Trowel	Coverage
Solid or Engineered	Solid: Max Thickness: 3/4" Max Width: 5' Eng: Max Thickness: 3/4" Max Width: Unlimited	1/4" x 1/4" V-Notch 	30-35 sq.ft. per gal.
		SCMB: 1/8" x 5/32" x 3/16" 	30-35 sq.ft. per gal.

For All-In-One Coverage: 100% adhesive coverage to concrete and 100% adhesive transfer to back of board is required

FOR USE WITH UNDERLAYMENT		
Flooring Type	Trowel	Coverage
Cork or rubber underlayment	1/8" x 1/8" Square notch* 	80 sq.ft. per gal.

*Recommended trowel size for 3.2mm material

- Coverage must be monitored to ensure accuracy of application. Trowel angle may prevent proper coverage.
- Applicator is responsible for periodic inspection of the trowel to check for excessive wear. Worn trowels must be replaced immediately.
- In case of uneven substrates, it may be necessary to use a notched trowel with bigger notches (avert hollow sections).
- Coverage must be monitored to ensure accuracy of application. Trowel angle may prevent proper coverage.
- Trowel size is recommended to obtain proper coverage larger sizes are acceptable. Excessive amounts of adhesive may cause wood flooring to slide while placing check coverage during installation.
- P5 trowels should be used at 90° angle, SC+MB trowel or 1/4 in. (6.3 mm) x 1/4 in. (6.3 mm) V-notch at 45° angle to subfloor to get stated coverages.

- Substrate Quality: Structurally sound, clean, dry, homogeneous, even, free from grease, dust and loose particles, paint, laitance, and other poorly adhering particles must be removed.
- The P5 and SC+MB trowel are available from Sika.

Sag Flow	Consistency: Spreads easily, holds ridges after troweling
Ambient Air Temperature	Room temperature between 60°F (15°C) and 90°F (35°C). For ambient temperatures the standard construction rules are relevant. Follow all wood floor manufacturer's acclimation and room temperature requirements.
Relative Air Humidity	Between 40% and 70% during installation is best for adhesive. See wood floor manufacturer for wood requirements.
Substrate Temperature	During laying and until SikaBond®-T17 has fully cured, substrate temperature should be greater than 60°F (15°C) and in case of radiant heating, less than 70°F (20°C). For substrate temperatures, the standard construction rules are relevant.
Substrate Moisture Content	For use as an adhesive only: SikaBond® T-17 is not affected by moisture or vapor transmission. For protection of the wood, follow the wood floor manufacturer's requirements for subfloor moisture. If substrate is not acceptable, use SikaBond® T-17 at recommended coverage rate as All-in-One or Sika® MB. See Technical Data Sheet for proper instruction. For use as an adhesive and membrane: Concrete moisture vapor emission rate (MVER) may not exceed 8 lbs. per 1,000 sq.ft. (5,44 kg per 92,9 m ²) per 24 hours, anhydrous calcium chloride test (ASTM F1869). Do not install when the relative humidity (RH) of the concrete slab exceeds 85% (ASTM F2170).
Curing Rate	4.0 mm/24 hrs. Floor may accept light foot traffic after 6–8 h (depending on climatic conditions and adhesive layer thickness)
Skin Time / Laying Time	~ 45–60 minutes

APPLICATION INSTRUCTIONS

SUBSTRATE PREPARATION

SikaBond®-T17 can be used on properly prepared, structurally sound concrete, cementitious patch/underlayments, chipboards, ceramic tiles, plywood. For on-grade sub-floors Sika® recommends the use of Sika® MB for best protection against sub-floor moisture – moisture testing is required by the wood flooring manufacturer for best results with the wood flooring products. Below grade applications are generally not recommended unless proper precautions are taken to protect the wood flooring from sub-floor and in-room humidity extremes. Sika recommends the use of Sika® MB over any dry, gypsum based sub-flooring to enhance surface strength. Preparation is a critical step in the installation process and will ensure a successful long term tenacious bond. All concrete, cement screed and gypsum based subfloors must be structurally sound, clean, dry, smooth; free of voids, projections, loose materials, oil, grease, sealers and other surface contaminants. Thoroughly clean with an industrial vacuum. Remove laitance or weak areas mechanically and thoroughly. For application over ceramic tiles it is necessary to grind tile surfaces and clean thoroughly with an industrial vacuum. For substrates with old well bonded adhesive or adhesive residue use Sika® MB – see

Sika® MB data sheet for installation instructions and proper details. If surface contains asphalt (cutback) adhesive, follow the Resilient Floor Covering Institute "Recommended Work Practices" for removal. When the asphalt (cutback) adhesive is sufficiently removed use the Sika® MB to help promote adhesion to the subfloor or use a Sika® Level patch/level product in conjunction with the correct primer. SikaBond®-T17 will adhere to most common patching/ levelling compounds. Due to differences in asphalt based adhesive types and performance capabilities, applicator must verify that preparation of the surface is sufficient prior to using Sika® MB or Sika Level patch/level compound. Due to differences in asphalt-based adhesive types and performance capabilities, applicators must verify that preparation of the surface is sufficient prior to using Sika® MB or Sika® Level patch/ level compound. For unknown substrates, please contact Sika® Technical Services for best practices at 1-800-933-SIKA.

APPLICATION METHOD / TOOLS

Read and understand data sheet completely before beginning installation. Follow all industry standards, as well as hardwood and bamboo flooring manufacturer's recommendations for floor flatness, acclimation, design, layout, application, etc. of wood flooring material. If jobsite conditions are outside of flooring manufacturer's

recommendations, take necessary corrective actions as recommended by the floor manufacturer to address these issues. Whether the moisture content of substrate exceeds or is within the manufacturer's recommendations, to address current or possible future subfloor moisture, apply SikaBond®-T17 as directed. SikaBond®-T17 is applied to the properly prepared substrate directly from the pail and uniformly distributed by trowel as described on this Product Data Sheet. Press the wood floor elements firmly into the adhesive so that the wood floor underside is sufficiently wetted. The elements can then be joined together using a rubber hammer and an impact block and/ or rubber mallet. Many types of wood floors have to be tapped from the top. Leave gaps at room perimeters and at any floor wall partition to allow wood flooring to move naturally – follow recommended guidelines from wood floor manufacturer. Spacers should be used to ensure perimeter space is maintained. The wood flooring manufacturer's laying instructions, acclimation requirements, room humidity/environmental control requirements as well as standard construction rules must be observed.

Removal

All tools must be cleaned immediately after use with SikaBond® Remover or standard industry cleaning solvent. Any adhesive that is permitted to cure on the tool will need to be removed by mechanical means. SikaBond Remover can be used to remove uncured or cured adhesive and fingerprints from wood surface.

LIMITATIONS

- Wood size limitations can be found in coverage section
- Room temperatures should be between 50 °F (10 °C) and 90 °F (35 °C) during installation unless otherwise specified limitations by wood flooring manufacturer.
- Do not use on wet, contaminated or friable substrates.
- When needed, Sika® recommends the use of Sika® Level patching and levelling compounds for best results.
- Gypsum based sub-floors are very susceptible to excess moisture and will be degraded if exposed to excess moisture from below or above.
- Below grade installations are typically more difficult to control moisture and room humidity levels – if this cannot be done sufficiently then below grade applications should use structurally sound engineered hardwood only.
- Do not use in areas subject to hydrostatic head or in areas subject to secondary source of moisture.
- Do not use over concrete with curing compounds, sealers or other surface treatments that could impact the adhesion.
- This adhesive will not prevent moisture related damage to wood flooring installations.
- Sub-floor should be level – do not use adhesive as a levelling agent.
- Contact with SikaBond® Remover will inhibit cure.
- Cutback or asphaltic based residue must be removed

before use of adhesive (refer to Resilient Floor Covering Institute Recommended Work Practices).

- Sufficient ambient moisture is necessary for proper curing.
- During laying, and until SikaBond®-T17 has fully cured, substrate temperature should be greater than 60 °F (15 °C). For substrate temperatures, the standard construction rules are relevant.
- Installations over radiant heat require that slab temperature be kept below 70 °F during installation and for 48 hours after installation – then raised slowly up to final desired temperature. Follow wood floor manufacturer's temperature guidelines.
- Do not install when moisture vapor emission rate (MVER) exceeds either wood flooring manufacturer's written requirement or 5 lb. (2.3 kg) per 1000 ft² (92.9 m²) per 24 hours.
- At recommended coverage rates, SikaBond®-T17 does not provide moisture protection.

Wood floors in non-insulated areas or areas without a moisture protection membrane, must only be installed after the application of Sika® MB to control the moisture, if within product limitations. For detailed instructions consult the Product Data Sheets or contact our Technical Service. In case of chemically pre-treated types of wood floors (e.g. ammonia, wood stain, timber preservative or woods that have been pre-sealed on the back side) and woods with high oil content SikaBond® should only be used if adhesion tests are run by applicator prior to starting application. Do not use on PE, PP, TEFLON, and certain plasticized synthetic materials. (Carry out pre-trials). Some primers can negatively influence the adhesion of SikaBond (pre-trials suggested). Do not expose SikaBond® to alcohol; this will impact the curing of the SikaBond®.

BASIS OF PRODUCT DATA

Results may differ based upon statistical variations depending upon mixing methods and equipment, temperature, application methods, test methods, actual site conditions and curing conditions.

OTHER RESTRICTIONS

See Legal Disclaimer.

ENVIRONMENTAL, HEALTH AND SAFETY

For further information and advice regarding transportation, handling, storage and disposal of chemical products, user should refer to the actual Safety Data Sheets containing physical, environmental, toxicological and other safety related data. User must read the current actual Safety Data Sheets before using any products. In case of an emergency, call CHEMTREC at 1-800-424-9300, International 703-527-3887.

DIRECTIVE 2004/42/CE - LIMITATION OF EMISSIONS OF VOC

53 g/L

LEGAL DISCLAIMER

- KEEP CONTAINER TIGHTLY CLOSED
- KEEP OUT OF REACH OF CHILDREN
- NOT FOR INTERNAL CONSUMPTION
- FOR INDUSTRIAL USE ONLY
- FOR PROFESSIONAL USE ONLY

Prior to each use of any product of Sika Corporation, its subsidiaries or affiliates ("SIKA"), the user must always read and follow the warnings and instructions on the product's most current product label, Product Data Sheet and Safety Data Sheet which are available at usa.sika.com or by calling SIKA's Technical Service Department at 800-933-7452. Nothing contained in any SIKA literature or materials relieves the user of the obligation to read and follow the warnings and instructions for each SIKA product as set forth in the current product label, Product Data Sheet and Safety Data Sheet prior to use of the SIKA product.

SIKA warrants this product for one year from date of installation to be free from manufacturing defects and to meet the technical properties on the current Product Data Sheet if used as directed within the product's shelf life. User determines suitability of product for intended use and assumes all risks. User's and/or buyer's sole remedy shall be limited to the purchase price or replacement of this product exclusive of any labor costs. **NO OTHER WARRANTIES EXPRESS OR IMPLIED SHALL APPLY INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. SIKA SHALL NOT BE LIABLE UNDER ANY LEGAL THEORY FOR SPECIAL OR CONSEQUENTIAL DAMAGES. SIKA SHALL NOT BE RESPONSIBLE FOR THE USE OF THIS PRODUCT IN A MANNER TO INFRINGE ON ANY PATENT OR ANY OTHER INTELLECTUAL PROPERTY RIGHTS HELD BY OTHERS.**

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Sika Corporation
201 Polito Avenue
Lyndhurst, NJ 07071
Phone: 800-933-7452
Fax: 201-933-6225

Sika Mexicana S.A. de C.V.
Carretera Libre Celaya Km. 8.5
Fracc. Industrial Balvanera
Corregidora, Queretaro
C.P. 76920
Phone: 52 442 2385800
Fax: 52 442 2250537

Sika Canada Inc.
601 Delmar Avenue
Pointe Claire
Quebec H9R 4A9
Phone: 514-697-2610
Fax: 514-694-2792



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